

South East Asia Technical Conference on Electronics Assembly

April 12-14, 2016 | Eastin Hotel | Penang, Malaysia



Register now and learn about new assembly technology, growing yield and increasing reliability.

This global conference is a strong technical three-day event focused on today's most important and timely issues in electronics manufacturing

Half-Day Training Workshops



Designing the Cleaning Process within the PCB Assembly Operations
Mike Bixenman, DBA., KYZEN Corporation



Industry 4.0 Smart Factory and Design Collaboration with Manufacturing
Jay Gorajia, Mentor Graphics Corporation



Solder Paste Evaluation (A review of How Solder Pastes are Evaluated)
Neil Poole, Henkel Electronic Materials LLC



Designing in Reliability by Assessing Contamination at the Component Interface
Mike Bixenman, DBA., KYZEN Corporation



It's Time for Low Temperature-Low Temperatures Solders, New Development and Their Applications
Ning-Cheng Lee, Ph.D., Indium Corporation



An Overview of the Factors and Mechanisms Impacting Reliability in HALT
Neil Poole, Henkel Electronic Materials LLC

Keynote Presentations

LEDs: The Future is Bright - Trends & Challenges in Manufacturing
Mohammed Khan, M.S., Lumileds

Nanotechnology in Electronics Packaging, Interconnect, and Assembly
Chuck Bauer, Ph.D., TechLead Corporation

Program Sessions

- » Solder Alloy for Reliability
- » LED Technology
- » Traceability and Test
- » High Reliability
- » Components and Microelectronics
- » Printing and Assembly
- » BGA and BTC
- » Harsh Environments

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